

Notice of References Cited

Application/Control No.

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Applicant(s)/Patent Under
Reexamination
DATTA, AMIT

Examiner

Edna Wong

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Art Unit

1753

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U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-			
	B	US-			
	C	US-			
	D	US-			
	E	US-			
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N	JP 56-154261 A *	11-1981	Japan	Mishima Kosan Co. Ltd.	-
	O					
	P					
	Q					
	R					
	S					
	T					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Chow et al., "Interdiffusion of Cu Substrate/ Electrodeposits for Cu/Co, Cu/Co-W, Cu/Co/Ni and Cu/Co-W/Ni Systems", Surface and Coatings Technology, Vol. 99, Issues 1-2, 5 February 1998, pp. 161-170.
	V	
	W	*Abstract Only.
	X	

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
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